ABSTRACT OF THE DISCLOSURE

An integrated heat sink/retention mechanism and a method for mounting a processor assembly on a circuit board using such an integrated heat sink/retention mechanism. The method involves attaching an integrated heat sink/retention mechanism onto the circuit board. A grounding connection may be formed between the circuit board and the integrated heat sink/retention mechanism. The integrated heat sink/retention mechanism is designed so that the heat sink is attachable to a processor assembly and mountable on a circuit board.

